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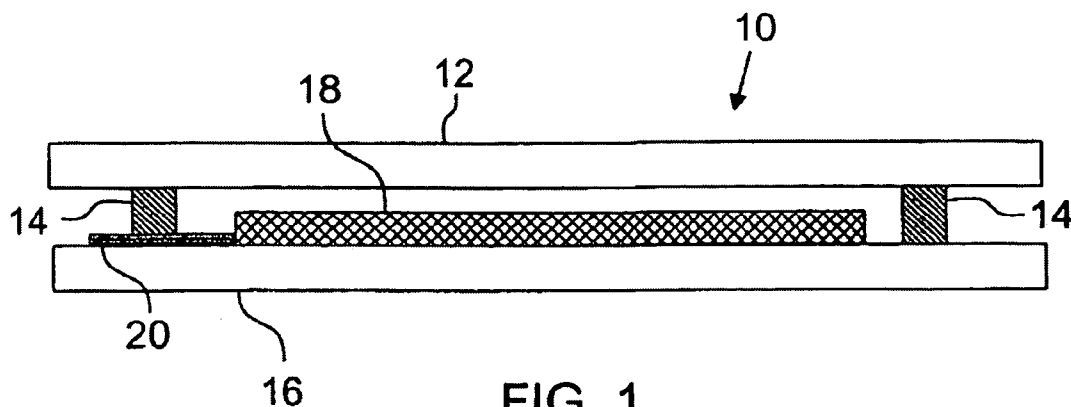


FIG. 1

(57) Abstract: Packages for elements, e.g., OLEDs, that are temperature sensitive are provided. The packages have a first glass substrate (12), a second glass substrate (16), and a wall (14) that separates the first and second substrates (12, 16) and hermetically seals at least one temperature sensitive element (18, 28, 36) between the substrates (12, 16). The wall (14) comprises a sintered frit and at least a portion of the wall is laser sealed to the second substrate (16) by melting a glass component of the sintered frit. The minimum width (40) of the laser-sealed portion of the wall (14) at any location along the wall (14) is greater than or equal to 2 millimeters so as to provide greater hermeticity and strength to the package. The laser sealing is performed without substantially degrading the temperature sensitive element(s) (18, 28, 36) housed in the package.